



Material Content Data Sheet



Sales Product Name		SPD30P06P G		Issued		22. January 2018		
MA#		MA001626196						
Package		PG-TO252-3-311		Weight*		314.98 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.913	1.24	1.24	12424	12424
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		136	
	non noble metal	iron	7439-89-6	0.143	0.05		455	
	non noble metal	copper	7440-50-8	143.098	45.42	45.48	454303	454894
	non noble metal	aluminium	7429-90-5	0.995	0.32	0.32	3158	3158
wire	inorganic material	antimonytrioxide	1309-64-4	1.969	0.63		6251	
encapsulation	plastics	brominated resin	-	2.110	0.67		6698	
	organic material	carbon black	1333-86-4	2.250	0.71		7144	
	plastics	epoxy resin	-	18.987	6.03		60279	
	inorganic material	silicondioxide	60676-86-0	115.328	36.61	44.65	366139	446511
leadfinish	non noble metal	tin	7440-31-5	3.740	1.19	1.19	11874	11874
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.086	0.03	0.03	274	275
solder	non noble metal	tin	7440-31-5	0.062	0.02		198	
	noble metal	silver	7440-22-4	0.078	0.02		248	
	non noble metal	lead	7439-92-1	2.978	0.95	0.99	9455	9901
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	iron	7439-89-6	0.019	0.01		61	
	non noble metal	copper	7440-50-8	19.177	6.09	6.10	60884	60963
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com